

Electronic Patent Application Fee Transmittal

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| Application Number: | 10598515 |
| Filing Date: | 01-Sep-2006 |
| Title of Invention: | Sealant Epoxy-Resin Molding Material, and Electronic Component Device |
| First Named Inventor/Applicant Name: | Seiichi Akagi |
| Filer: | Joerg-Uwe V. Szipl |
| Attorney Docket Number: | MIYOSH0008 |

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|--|----------|----------|--------|----------------------|
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 130 | 130 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Miscellaneous: | | | | |
| Request for continued examination | 1801 | 1 | 810 | 810 |
| Total in USD (\$) | | | | 940 |